

FILED ELECTRONICALLY ON 22 MAY 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS) Examiner: Chris C. CHU
Application No.: 10/632,552)
Filed: August 2, 2003) Group Art Unit: 2815
Title: **Semiconductor multi-package module having**)
package stacked over die-up flip chip)
ball grid array package and having wire)
bond interconnect between stacked packages)
) Date: May 22, 2006.

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O Box 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed December 20, 2005, kindly amend the application as follows.

Amendments to the Claims are reflected in the **Listing of Claims** which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.